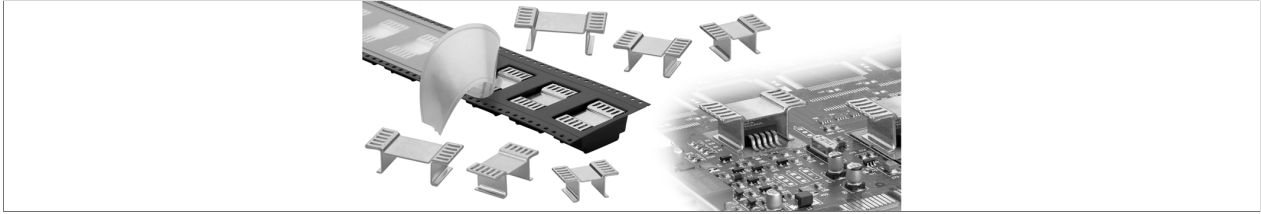


A

Heatsinks for D PAK and others

B



C

- copper heatsinks with excellent heat conductivity
- direct mounting on printed circuit through solderable surface
- especially suitable for SMD components of type D PAK (TO 252), D² PAK (TO 263), D³ PAK (TO 268), SOT 669 LF PAK, SO IC-8 FL MP, Power SO-8, Power SO-10, Power SO-20, Power SO-36, SO-14, SO-16, SOT 223 etc
- available standard packing: loose parts or reel
- special packing like magazine, tray etc. on request
- special versions according to customers specifications
- **tape width:** 44 mm, **reel diameter:** 330 mm, **quantity:** FK 244 08 = 325, FK 244 13 = 200

D

E

art. no.			31,5 K/W
FK 244 08 D PAK ... weight: 2 g			
art. no.			25 K/W
FK 244 13 D PAK ... weight: 3.3 g			
art. no.			29,3 K/W
FK 244 08 D2 PAK ... weight: 2.2 g			
art. no.			22,8 K/W
FK 244 13 D2 PAK ... weight: 3.6 g			
art. no.			26 K/W
FK 244 08 D3 PAK ... weight: 2.5 g			
art. no.			19,5 K/W
FK 244 13 D3 PAK ... weight: 3.9 g			
please indicate:	... packing (option) TR=tape and reel		

M

material: copper (Cu)
material thickness: 0.6 mm
surface treatment: solderable

N

C 17

Heatsinks for transistors
 Heatsinks for TO 5 and TO 18
 Attachable heatsinks
 Finger-shaped heatsinks

→ C 4 - 9
 → C 15 - 16
 → C 10 - 14
 → C 2 - 3

High capacity heatsinks
 Designed parts out of aluminium
 Heatsink profile-overview
 Classification table

→ A 54 - 55
 → A 135
 → A 13 - 16
 → A 18 - 20